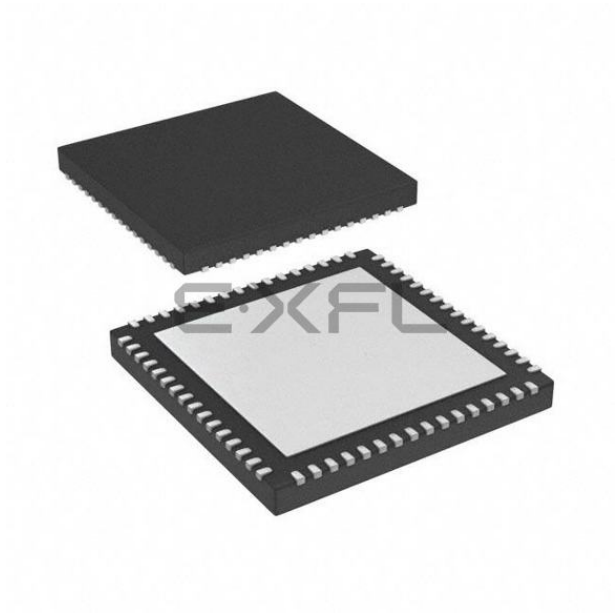
Microchip Technology - PIC24FJ1024GA606T-I/MR Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, HLVD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	1MB (341.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj1024ga606t-i-mr

TABLE 1-3: PIC24FJ1024GA610/GB610 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Pin Function	Pin Number/Grid Locator						I/O	Input Buffer	Description
	GA606 64-Pin QFN/TQFP/ QFP	GB606 64-Pin QFN/ TQFP/QFP	GA610 100-Pin TQFP/ QFP	GB610 100-Pin TQFP/ QFP	GA612 121-Pin BGA	GB612 121-Pin BGA			
RD0	46	46	72	72	D9	D9	I/O	DIG/ST	PORTD Digital I/Os
RD1	49	49	76	76	A11	A11	I/O	DIG/ST	
RD2	50	50	77	77	A10	A10	I/O	DIG/ST	
RD3	51	51	78	78	B9	B9	I/O	DIG/ST	
RD4	52	52	81	81	C8	C8	I/O	DIG/ST	
RD5	53	53	82	82	B8	B8	I/O	DIG/ST	
RD6	54	54	83	83	D7	D7	I/O	DIG/ST	
RD7	55	55	84	84	C7	C7	I/O	DIG/ST	
RD8	42	42	68	68	E9	E9	I/O	DIG/ST	
RD9	43	43	69	69	E10	E10	I/O	DIG/ST	
RD10	44	44	70	70	D11	D11	I/O	DIG/ST	
RD11	45	45	71	71	C11	C11	I/O	DIG/ST	
RD12	—	—	79	79	A9	A9	I/O	DIG/ST	
RD13	—	—	80	80	D8	D8	I/O	DIG/ST	
RD14	—	—	47	47	L9	L9	I/O	DIG/ST	
RD15	—	—	48	48	K9	K9	I/O	DIG/ST	
RE0	60	60	93	93	A4	A4	I/O	DIG/ST	PORTE Digital I/Os
RE1	61	61	94	94	B4	B4	I/O	DIG/ST	
RE2	62	62	98	98	B3	B3	I/O	DIG/ST	
RE3	63	63	99	99	A2	A2	I/O	DIG/ST	
RE4	64	64	100	100	A1	A1	I/O	DIG/ST	
RE5	1	1	3	3	D3	D3	I/O	DIG/ST	
RE6	2	2	4	4	C1	C1	I/O	DIG/ST	
RE7	3	3	5	5	D2	D2	I/O	DIG/ST	
RE8	—	—	18	18	G1	G1	I/O	DIG/ST	
RE9	—	—	19	19	G2	G2	I/O	DIG/ST	
REFI	24	24	35	35	J5	J5	I	ST	Reference Clock Input

Legend: TTL = TTL input buffer
ANA = Analog level input/output
DIG = Digital input/output
ST = Schmitt Trigger input buffer
I^2C = I^2C/SMBus input buffer
XCVR = Dedicated Transceiver

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 16V-50V capacitor is recommended. The capacitor should be a low-ESR device with a self-resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including microcontrollers to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

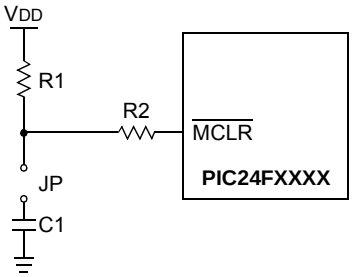
2.3 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides two specific device functions: device Reset, and device programming and debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{MCLR}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the external capacitor, C, in the event of a $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

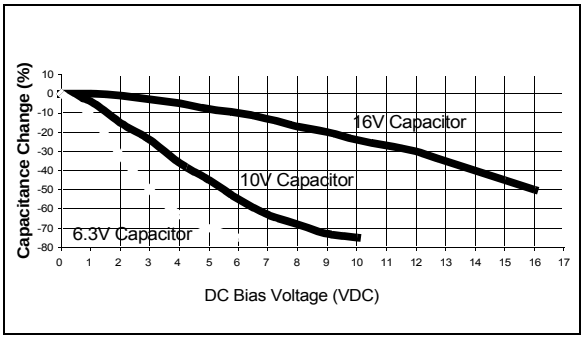
Typical low-cost, 10 μF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R) or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 μF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at a minimum of 16V for the 1.8V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming (ICSP) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

For device emulation, ensure that the "Communication Channel Select" pins (i.e., PGECx/PGEDx), programmed into the device, match the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 31.0 "Development Support"**.

3.3 Arithmetic Logic Unit (ALU)

The PIC24F ALU is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are 2's complement in nature. Depending on the operation, the ALU may affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as Borrow and Digit Borrow bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array, or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

The PIC24F CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit divisor division.

3.3.1 MULTIPLIER

The ALU contains a high-speed, 17-bit x 17-bit multiplier. It supports unsigned, signed or mixed sign operation in several multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.3.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

1. 32-bit signed/16-bit signed divide
2. 32-bit unsigned/16-bit unsigned divide
3. 16-bit signed/16-bit signed divide
4. 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. The 16-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn), and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.3.3 MULTI-BIT SHIFT SUPPORT

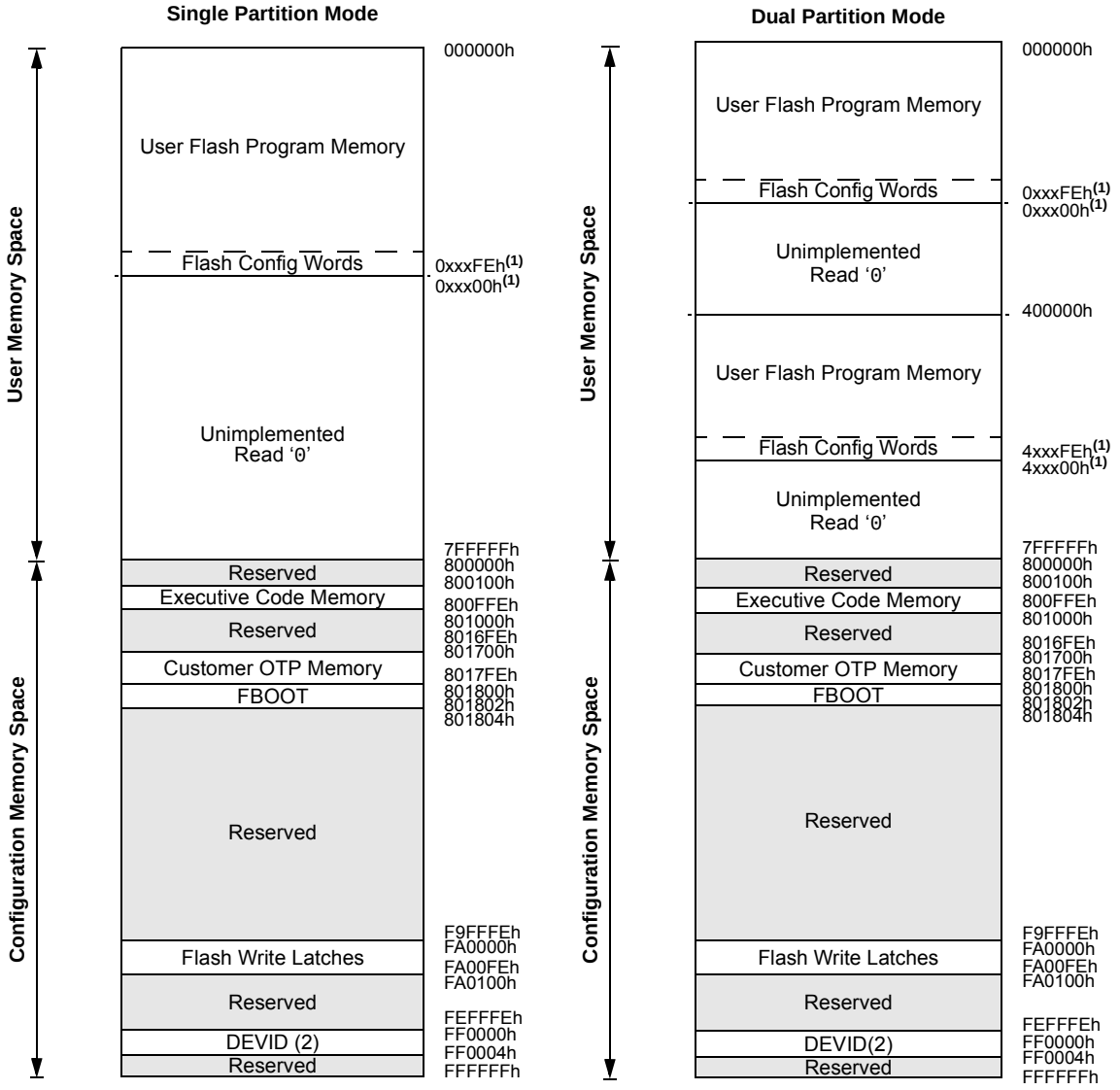
The PIC24F ALU supports both single bit and single-cycle, multi-bit arithmetic and logic shifts. Multi-bit shifts are implemented using a shifter block, capable of performing up to a 15-bit arithmetic right shift, or up to a 15-bit left shift, in a single cycle. All multi-bit shift instructions only support Register Direct Addressing for both the operand source and result destination.

A full summary of instructions that use the shift operation is provided in Table 3-2.

TABLE 3-2: INSTRUCTIONS THAT USE THE SINGLE BIT AND MULTI-BIT SHIFT OPERATION

Instruction	Description
ASR	Arithmetic Shift Right Source register by one or more bits.
SL	Shift Left Source register by one or more bits.
LSR	Logical Shift Right Source register by one or more bits.

FIGURE 4-1: PROGRAM SPACE MEMORY MAP FOR PIC24FJ1024GA610/GB610 FAMILY DEVICES



Legend: Memory areas are not shown to scale.

Note 1: Exact boundary addresses are determined by the size of the implemented program memory (Table 4-1).

TABLE 4-1: PROGRAM MEMORY SIZES AND BOUNDARIES(1)

Device	Program Memory Upper Boundary (Instruction Words)			Write Blocks(2)	Erase Blocks(2)
	Single Partition Mode	Dual Partition Mode			
		Active Partition	Inactive Partition		
PIC24FJ1024GX6XX	0ABFFEh (352K)	055FFEh (176K)	455FFEh (176K)	2752	344
PIC24FJ512GX6XX	055FFEh (176K)	02AFFEh (88k)	42AFFEh (88k)	1376	172
PIC24FJ256GX6XX	02AFFEh (88K)	0157FEh (44k)	4157FEh (44k)	688	86
PIC24FJ128GX6XX	015FFEh (44K)	00AFFEh (22k)	40AFFEh (22k)	352	44

Note 1: Includes Flash Configuration Words.

2: 1 Write Block = 128 Instruction Words; 1 Erase Block = 1024 Instruction Words.

FIGURE 4-2: RELATIONSHIP BETWEEN PARTITIONS 1/2 AND ACTIVE/INACTIVE PARTITIONS

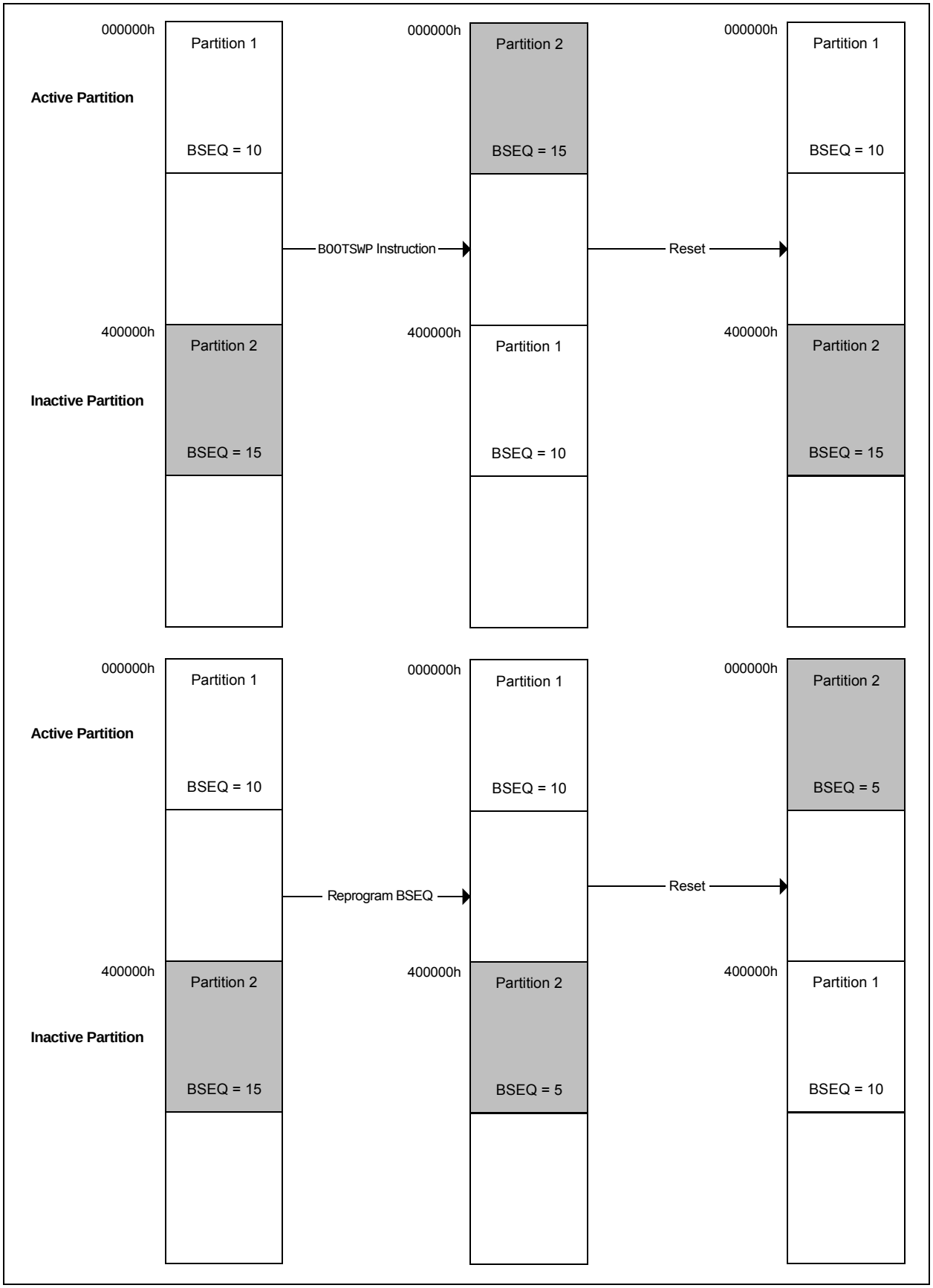


TABLE 4-7: SFR MAP: 0300h BLOCK

File Name	Address	All Resets	File Name	Address	All Resets
SINGLE OUTPUT CAPTURE/COMPARE/PWM			**SINGLE OUTPUT CAPTURE/COMPARE/PWM (CONTINUED)**		
CCP4CON1L	0300	0000	CCP6STATH	0356	0000
CCP4CON1H	0302	0000	CCP6TMRL	0358	0000
CCP4CON2L	0304	0000	CCP6TMRH	035A	0000
CCP4CON2H	0306	0100	CCP6PRL	035C	FFFF
CCP4CON3L	0308	0000	CCP6PRH	035E	FFFF
CCP4CON3H	030A	0000	CCP6RAL	0360	0000
CCP4STATL	030C	00x0	CCP6RAH	0362	0000
CCP4STATH	030E	0000	CCP6RBL	0364	0000
CCP4TMRL	0310	0000	CCP6RBH	0366	0000
CCP4TMRH	0312	0000	CCP6BUFL	0368	0000
CCP4PRL	0314	FFFF	CCP6BUFH	036A	0000
CCP4PRH	0316	FFFF	CCP7CON1L	036C	0000
CCP4RAL	0318	0000	CCP7CON1H	036E	0000
CCP4RAH	031A	0000	CCP7CON2L	0370	0000
CCP4RBL	031C	0000	CCP7CON2H	0372	0100
CCP4RBH	031E	0000	CCP7CON3L	0374	0000
CCP4BUFL	0320	0000	CCP7CON3H	0376	0000
CCP4BUFH	0322	0000	CCP7STATL	0378	00x0
CCP5CON1L	0324	0000	CCP7STATH	037A	0000
CCP5CON1H	0326	0000	CCP7TMRL	037C	0000
CCP5CON2L	0328	0000	CCP7TMRH	037E	0000
CCP5CON2H	032A	0100	CCP7PRL	0380	FFFF
CCP5CON3L	032C	0000	CCP7PRH	0382	FFFF
CCP5CON3H	032E	0000	CCP7RAL	0384	0000
CCP5STATL	0330	00x0	CCP7RAH	0386	0000
CCP5STATH	0332	0000	CCP7RBL	0388	0000
CCP5TMRL	0334	0000	CCP7RBH	038A	0000
CCP5TMRH	0336	0000	CCP7BUFL	038C	0000
CCP5PRL	0338	FFFF	CCP7BUFH	038E	0000
CCP5PRH	033A	FFFF	**UART**		
CCP5RAL	033C	0000	U1MODE	0398	0000
CCP5RAH	033E	0000	U1STA	039A	0110
CCP5RBL	0340	0000	U1TXREG	039C	x0xx
CCP5RBH	0342	0000	U1RXREG	039E	0000
CCP5BUFL	0344	0000	U1BRG	03A0	0000
CCP5BUFH	0346	0000	U1ADMD	03A2	0000
CCP6CON1L	0348	0000	U2MODE	03AE	0000
CCP6CON1H	034A	0000	U2STA	03B0	0110
CCP6CON2L	034C	0000	U2TXREG	03B2	xxxx
CCP6CON2H	034E	0100	U2RXREG	03B4	0000
CCP6CON3L	0350	0000	U2BRG	03B6	0000
CCP6CON3H	0352	0000	U2ADMD	03B8	0000
CCP6STATL	0354	00x0	U3MODE	03C4	0000

Legend: — = unimplemented, read as '0'; x = undefined. Reset values are shown in hexadecimal.

REGISTER 6-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/S-0, HC(1)	R/W-0(1)	R-0, HSC(1)	r-0	R-0, HSC(1,3)	R-0(1)	U-0	U-0
WR	WREN	WRERR	—	SFTSWP	P2ACTIV	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)
—	—	—	—	NVMOP3(2)	NVMOP2(2)	NVMOP1(2)	NVMOP0(2)
bit 7							bit 0

Legend:	S = Settable bit	HC = Hardware Clearable bit	r = Reserved bit
R = Readable bit	W = Writable bit	'0' = Bit is cleared	x = Bit is unknown
-n = Value at POR	'1' = Bit is set	U = Unimplemented bit, read as '0'	
HSC = Hardware Settable/Clearable bit			

bit 15 **WR:** Write Control bit(1,4)
- 1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit(1)
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit(1)
- 1 = An improper program or erase sequence attempt, or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12 **Reserved:** Maintain as '0'

bit 11 **SFTSWP:** Soft Swap Status bit(1,3)

In Single Partition Mode:
Read as '0'.

In Dual Partition Mode:
- 1 = Partitions have been successfully swapped using the BOOTSWP instruction
- 0 = Awaiting successful panel swap using the BOOTSWP instruction

bit 10 **P2ACTIV:** Dual Partition Active Status bit(1)

In Single Partition Mode:
Read as '0'.

In Dual Partition Mode:
- 1 = Partition 2 is mapped into the active region
- 0 = Partition 1 is mapped into the active region

bit 9-4 **Unimplemented:** Read as '0'

Note 1: These bits can only be reset on a Power-on Reset.

2: All other combinations of NVMOP<3:0> are unimplemented.

3: This bit may be cleared by software or by any Reset.

4: The WR bit should always be polled to indicate completion during any Flash memory program or erase operation while in Single Partition Mode.

TABLE 7-3: RESET DELAY TIMES FOR VARIOUS DEVICE RESETS

Reset Type	Clock Source	$\overline{\text{SYSRST}}$ Delay	System Clock Delay	Notes
POR	EC	TPOR + TSTARTUP + TRST	—	**1, 2, 3**
	ECPLL	TPOR + TSTARTUP + TRST	TLOCK	**1, 2, 3, 5**
	XT, HS, SOSC	TPOR + TSTARTUP + TRST	TOST	**1, 2, 3, 4**
	XTPLL, HSPLL	TPOR + TSTARTUP + TRST	TOST + TLOCK	**1, 2, 3, 4, 5**
	FRC, OSCFDIV	TPOR + TSTARTUP + TRST	TFRC	**1, 2, 3, 6, 7**
	FRCPLL	TPOR + TSTARTUP + TRST	TFRC + TLOCK	**1, 2, 3, 5, 6**
	LPRC	TPOR + TSTARTUP + TRST	TLPRC	**1, 2, 3, 6**
	DCO	TPOR + TSTARTUP + TRST	TDCO	**1, 2, 3, 8**
BOR	EC	TSTARTUP + TRST	—	**2, 3**
	ECPLL	TSTARTUP + TRST	TLOCK	**2, 3, 5**
	XT, HS, SOSC	TSTARTUP + TRST	TOST	**2, 3, 4**
	XTPLL, HSPLL	TSTARTUP + TRST	TOST + TLOCK	**2, 3, 4, 5**
	FRC, OSCFDIV	TSTARTUP + TRST	TFRC	**2, 3, 6, 7**
	FRCPLL	TSTARTUP + TRST	TFRC + TLOCK	**2, 3, 5, 6**
	LPRC	TSTARTUP + TRST	TLPRC	**2, 3, 6**
	DCO	TPOR + TSTARTUP + TRST	TDCO	**1, 2, 3, 8**
$\overline{\text{MCLR}}$	Any Clock	TRST	—	**3**
WDT	Any Clock	TRST	—	**3**
Software	Any clock	TRST	—	**3**
Illegal Opcode	Any Clock	TRST	—	**3**
Uninitialized W	Any Clock	TRST	—	**3**
Trap Conflict	Any Clock	TRST	—	**3**

Note 1: TPOR = Power-on Reset Delay (10 μs nominal).

2: TSTARTUP = TVREG.

3: TRST = Internal State Reset Time (2 μs nominal).

4: TOST = Oscillator Start-up Timer (OST). A 10-bit counter counts 1024 oscillator periods before releasing the oscillator clock to the system.

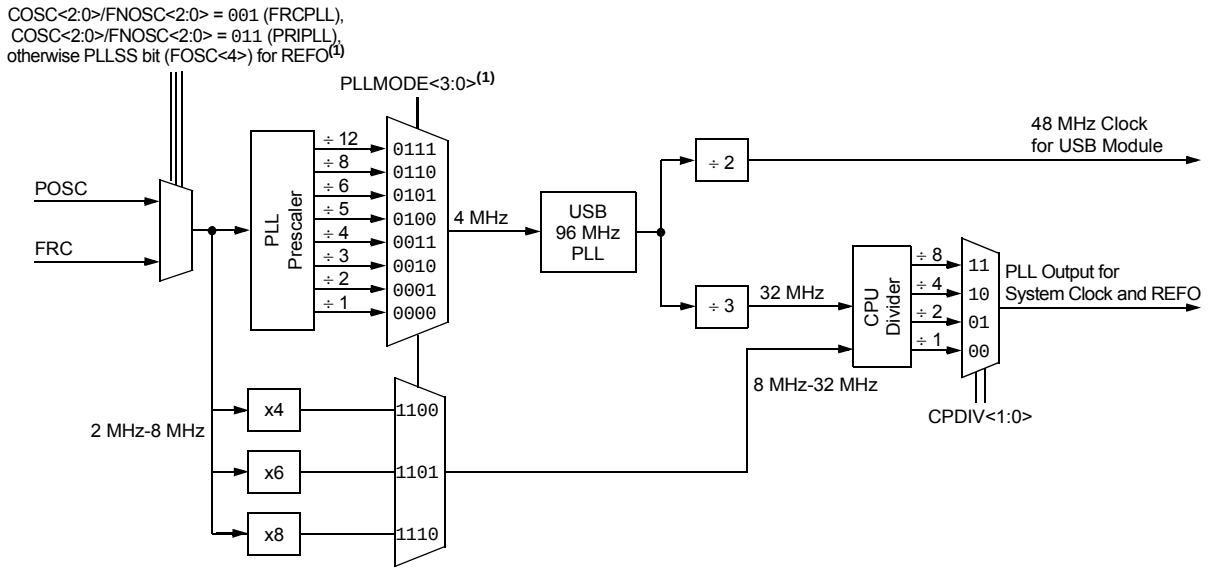
5: TLOCK = PLL Lock Time.

6: TFRC and TLPRC = RC Oscillator Start-up Times.

7: If Two-Speed Start-up is enabled, regardless of the Primary Oscillator selected, the device starts with FRC so the system clock delay is just TFRC, and in such cases, FRC start-up time is valid; it switches to the Primary Oscillator after its respective clock delay.

8: TDCO = DCO Start-up and Stabilization Times.

FIGURE 9-2: PLL BLOCK



Note 1: The FNOSC<2:0>, PLLMODE<3:0> and PLLSS bits are in the configuration area. See the FOSC and FOSCSEL Configuration registers (Register 30-6 and Register 30-7) for more information.

NOTES:

14.1.2 CASCADED (32-BIT) MODE

By default, each module operates independently with its own 16-bit timer. To increase resolution, adjacent even and odd modules can be configured to function as a single 32-bit module. (For example, Modules 1 and 2 are paired, as are Modules 3 and 4, and so on.) The odd numbered module (ICx) provides the Least Significant 16 bits of the 32-bit register pairs and the even numbered module (ICy) provides the Most Significant 16 bits. Wrap-arounds of the ICx registers cause an increment of their corresponding ICy registers.

Cascaded operation is configured in hardware by setting the IC32 bits (ICxCON2<8>) for both modules.

14.2 Capture Operations

The input capture module can be configured to capture timer values and generate interrupts on rising edges on ICx or all transitions on ICx. Captures can be configured to occur on all rising edges or just some (every 4th or 16th). Interrupts can be independently configured to generate on each event or a subset of events.

To set up the module for capture operations:

1. Configure the ICx input for one of the available Peripheral Pin Select pins.
2. If Synchronous mode is to be used, disable the Sync source before proceeding.
3. Make sure that any previous data has been removed from the FIFO by reading ICxBUF until the ICBNE bit (ICxCON1<3>) is cleared.
4. Set the SYNCSELx bits (ICxCON2<4:0>) to the desired Sync/Trigger source.
5. Set the ICTSELx bits (ICxCON1<12:10>) for the desired clock source.
6. Set the ICIx bits (ICxCON1<6:5>) to the desired interrupt frequency.
7. Select Synchronous or Trigger mode operation:
   a) Check that the SYNCSELx bits are not set to '00000'.
   b) For Synchronous mode, clear the ICTRIG bit (ICxCON2<7>).
   c) For Trigger mode, set ICTRIG and clear the TRIGSTAT bit (ICxCON2<6>).
8. Set the ICMx bits (ICxCON1<2:0>) to the desired operational mode.
9. Enable the selected Sync/Trigger source.

For 32-bit cascaded operations, the setup procedure is slightly different:

1. Set the IC32 bits for both modules (ICyCON2<8> and ICxCON2<8>), enabling the even numbered module first. This ensures the modules will start functioning in unison.
2. Set the ICTSELx and SYNCSELx bits for both modules to select the same Sync/Trigger and time base source. Set the even module first, then the odd module. Both modules must use the same ICTSELx and SYNCSELx bits settings.
3. Clear the ICTRIG bit of the even module (ICyCON2<7>). This forces the module to run in Synchronous mode with the odd module, regardless of its Trigger setting.
4. Use the odd module's ICIx bits (ICxCON1<6:5>) to set the desired interrupt frequency.
5. Use the ICTRIG bit of the odd module (ICxCON2<7>) to configure Trigger or Synchronous mode operation.

Note:	For Synchronous mode operation, enable the Sync source as the last step. Both input capture modules are held in Reset until the Sync source is enabled.

6. Use the ICMx bits of the odd module (ICxCON1<2:0>) to set the desired Capture mode.

The module is ready to capture events when the time base and the Sync/Trigger source are enabled. When the ICBNE bit (ICxCON1<3>) becomes set, at least one capture value is available in the FIFO. Read input capture values from the FIFO until the ICBNE clears to '0'.

For 32-bit operation, read both the ICxBUF and ICyBUF for the full 32-bit timer value (ICxBUF for the lsw, ICyBUF for the msw). At least one capture value is available in the FIFO buffer when the odd module's ICBNE bit (ICxCON1<3>) becomes set. Continue to read the buffer registers until ICBNE is cleared (performed automatically by hardware).

REGISTER 17-1: SPIxCON1L: SPIx CONTROL REGISTER 1 LOW (CONTINUED)

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
1 = Transmit happens on transition from active clock state to Idle clock state
0 = Transmit happens on transition from Idle clock state to active clock state

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{SSx}$ pin is used by the macro in Slave mode; $\overline{SSx}$ pin is used as the slave select input
0 = $\overline{SSx}$ pin is not used by the macro ($\overline{SSx}$ pin will be controlled by the port I/O)

bit 6 **CKP:** SPIx Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

bit 4 **DISSDI:** Disable SDIx Input Port bit
1 = SDIx pin is not used by the module; pin is controlled by the port function
0 = SDIx pin is controlled by the module

bit 3 **DISSCK:** Disable SCKx Output Port bit
1 = SCKx pin is not used by the module; pin is controlled by the port function
0 = SCKx pin is controlled by the module

bit 2 **MCLKEN:** Master Clock Enable bit(3)
1 = REFO output is used by the BRG
0 = Peripheral clock is used by the BRG

bit 1 **SPIFE:** Frame Sync Pulse Edge Select bit
1 = Frame Sync pulse (Idle-to-active edge) coincides with the first bit clock
0 = Frame Sync pulse (Idle-to-active edge) precedes the first bit clock

bit 0 **ENHBUF:** Enhanced Buffer Mode Enable bit
1 = Enhanced Buffer mode is enabled
0 = Enhanced Buffer mode is disabled

Note 1: When AUDEN = 1, this module functions as if CKE = 0, regardless of its actual value.
2: When FRMEN = 1, SSEN is not used.
3: MCLKEN can only be written when the SPIEN bit = 0.
4: This channel is not meaningful for DSP/PCM mode as LRC follows the FRMSYPW bit.

REGISTER 20-4: U1OTGCON: USB ON-THE-GO CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	r-0	R/W-0	r-0	R/W-0
DPPULUP	DMPULUP	DPPULDWN(1)	DMPULDWN(1)	—	OTGEN(1)	—	VBUSDIS(1)
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **DPPULUP:** D+ Pull-up Enable bit
1 = D+ data line pull-up resistor is enabled
0 = D+ data line pull-up resistor is disabled

bit 6 **DMPULUP:** D- Pull-up Enable bit
1 = D- data line pull-up resistor is enabled
0 = D- data line pull-up resistor is disabled

bit 5 **DPPULDWN:** D+ Pull-Down Enable bit(1)
1 = D+ data line pull-down resistor is enabled
0 = D+ data line pull-down resistor is disabled

bit 4 **DMPULDWN:** D- Pull-Down Enable bit(1)
1 = D- data line pull-down resistor is enabled
0 = D- data line pull-down resistor is disabled

bit 3 **Reserved:** Maintain as '0'

bit 2 **OTGEN:** OTG Features Enable bit(1)
1 = USB OTG is enabled; all D+/D- pull-up and pull-down bits are enabled
0 = USB OTG is disabled; D+/D- pull-up and pull-down bits are controlled in hardware by the settings of the HOSTEN and USBEN (U1CON<3,0>) bits

bit 1 **Reserved:** Maintain as '0'

bit 0 **VBUSDIS:** VBUS Discharge Enable bit(1)
1 = VBUS line is discharged through a resistor
0 = VBUS line is not discharged

Note 1: These bits are only used in Host mode; do not use in Device mode.

REGISTER 20-13: U1CNFG2: USB CONFIGURATION REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
—	—	—	PUVBUS	EXTI2CEN	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4 **PUVBUS:** VBUS Pull-Up Enable bit
1 = Pull-up on VBUS pin is enabled
0 = Pull-up on VBUS pin is disabled

bit 3 **EXTI2CEN:** I^2C Interface for External Module Control Enable bit
1 = External module(s) is controlled via the I^2C interface
0 = External module(s) is controlled via the dedicated pins

bit 2-0 **Unimplemented:** Read as '0'

20.7.2 USB INTERRUPT REGISTERS

REGISTER 20-14: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER (HOST MODE ONLY)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/K-0, HS	R/K-0, HS	R/K-0, HS	R/K-0, HS	R/K-0, HS	R/K-0, HS	U-0	R/K-0, HS
IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	K = Write ‘1’ to Clear bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **IDIF:** ID State Change Indicator bit
1 = Change in ID state is detected
0 = No ID state change is detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit
1 = The 1 millisecond timer has expired
0 = The 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit
1 = USB line state (as defined by the SE0 and JSTATE bits) has been stable for 1 ms, but different from the last time
0 = USB line state has not been stable for 1 ms

bit 4 **ACTVIF:** Bus Activity Indicator bit
1 = Activity on the D+/D- lines or VBUS is detected
0 = No activity on the D+/D- lines or VBUS is detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit
1 = VBUS has crossed VA_SESS_END (as defined in the *“USB 2.0 Specification”*)**(1)**
0 = VBUS has not crossed VA_SESS_END

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit
1 = VBUS change on B-device is detected; VBUS has crossed VB_SESS_END (as defined in the *“USB 2.0 Specification”*)**(1)**
0 = VBUS has not crossed VB_SESS_END

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit
1 = VBUS change on A-device is detected; VBUS has crossed VA_VBUS_VLD (as defined in the *“USB 2.0 Specification”*)**(1)**
0 = No VBUS change on A-device is detected

Note 1: VBUS threshold crossings may either be rising or falling.

Note: Individual bits can only be cleared by writing a ‘1’ to the bit position as part of a word write operation on the entire register. Using Boolean instructions or bitwise operations to write to a single bit position will cause all set bits, at the moment of the write, to become cleared.

TABLE 21-2: ENHANCED PARALLEL MASTER PORT PIN DESCRIPTIONS

Pin Name (Alternate Function)	Type	Description
PMA<22:16>	O	Address Bus bits<22:16>
PMA15	O	Address Bus bit 15
	I/O	Data Bus bit 15 (16-bit port with Multiplexed Addressing)
(PMCS2)	O	Chip Select 2 (alternate location)
PMA14	O	Address Bus bit 14
	I/O	Data Bus bit 14 (16-bit port with Multiplexed Addressing)
(PMCS1)	O	Chip Select 1 (alternate location)
PMA<13:8>	O	Address Bus bits<13:8>
	I/O	Data Bus bits<13:8> (16-bit port with Multiplexed Addressing)
PMA<7:3>	O	Address Bus bits<7:3>
PMA2 (PMALU)	O	Address Bus bit 2
	O	Address Latch Upper Strobe for Multiplexed Address
PMA1 (PMALH)	I/O	Address Bus bit 1
	O	Address Latch High Strobe for Multiplexed Address
PMA0 (PMALL)	I/O	Address Bus bit 0
	O	Address Latch Low Strobe for Multiplexed Address
PMD<15:8>	I/O	Data Bus bits<15:8> (Demultiplexed Addressing)
PMD<7:4>	I/O	Data Bus bits<7:4>
	O	Address Bus bits<7:4> (4-bit port with 1-Phase Multiplexed Addressing)
PMD<3:0>	I/O	Data Bus bits<3:0>
PMCS1(1)	O	Chip Select 1
PMCS2(1)	O	Chip Select 2
PMWR	I/O	Write Strobe(2)
(PMENB)	I/O	Enable Signal(2)
PMRD	I/O	Read Strobe(2)
(PMRD/$\overline{\text{PMWR}}$)	I/O	Read/$\overline{\text{Write}}$ Signal(2)
PMBE1	O	Byte Indicator
PMBE0	O	Nibble or Byte Indicator
PMACK1	I	Acknowledgment Signal 1
PMACK2	I	Acknowledgment Signal 2

Note 1: These pins are implemented in 100-pin and 121-pin devices only.

2: Signal function depends on the setting of the MODE<1:0> and SM bits (PMCON1<9:8> and PMCSxCF<8>).

REGISTER 22-5: RTCCON3L: RTCC CONTROL REGISTER 3 (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PWCSAMP7	PWCSAMP6	PWCSAMP5	PWCSAMP4	PWCSAMP3	PWCSAMP2	PWCSAMP1	PWCSAMP0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PWCSTAB7	PWCSTAB6	PWCSTAB5	PWCSTAB4	PWCSTAB3	PWCSTAB2	PWCSTAB1	PWCSTAB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **PWCSAMP<7:0>:** Power Control Sample Window Timer bits
11111111 = Sample window is always enabled, even when PWCEN = 0
11111110 = Sample window is 254 TPWCCLK clock periods
•
•
•
00000001 = Sample window is 1 TPWCCLK clock period
00000000 = No sample window

bit 7-0 **PWCSTAB<7:0>:** Power Control Stability Window Timer bits(1)
11111111 = Stability window is 255 TPWCCLK clock periods
11111110 = Stability window is 254 TPWCCLK clock periods
•
•
•
00000001 = Stability window is 1 TPWCCLK clock period
00000000 = No stability window; sample window starts when the alarm event triggers

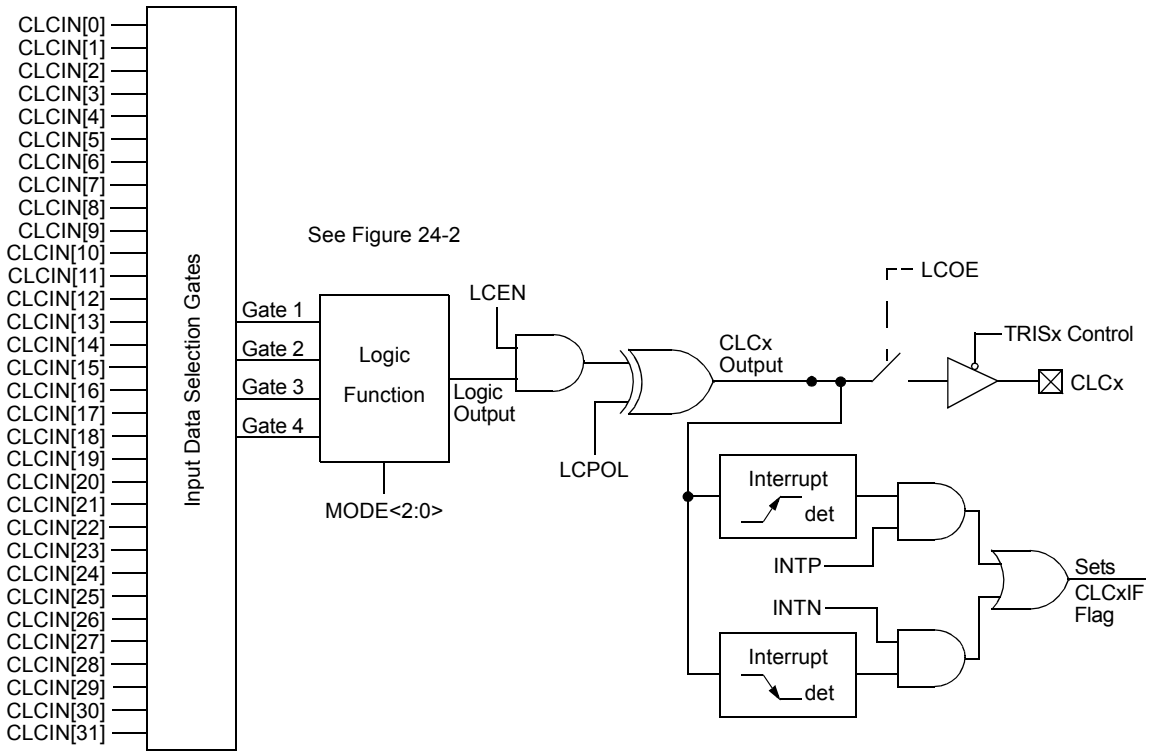
Note 1: The sample window always starts when the stability window timer expires, except when its initial value is 00h.

24.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLC) module allows the user to specify combinations of signals as inputs to a logic function and to use the logic output to control other peripherals or I/O pins. This provides greater flexibility and potential in embedded designs, since the CLC module can operate outside the limitations of software execution and supports a vast amount of output designs.

There are four input gates to the selected logic function. These four input gates select from a pool of up to 32 signals that are selected using four data source selection multiplexers. Figure 24-1 shows an overview of the module. Figure 24-3 shows the details of the data source multiplexers and logic input gate connections.

FIGURE 24-1: CLCx MODULE



Note: All register bits shown in this figure can be found in the CLCxCONL register.

REGISTER 25-1: AD1CON1: A/D CONTROL REGISTER 1 (CONTINUED)

bit 1 **SAMP:** A/D Sample Enable bit
1 = A/D Sample-and-Hold amplifiers are sampling
0 = A/D Sample-and-Hold amplifiers are holding

bit 0 **DONE:** A/D Conversion Status bit
1 = A/D conversion cycle has completed
0 = A/D conversion cycle has not started or is in progress

Note 1: This bit is only available when Extended DMA and buffer features are available (DMAEN = 1).